

FAST - (1002390.wsp.1)

File View Edit Tools Window Help

DBs: USPAT:US-PGPUB EPO, JPO, IBM, TDB

Default operator: OR

Highlight all hits in history

(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (((("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor)) and (source and drain and gate)) and (second adj portion)

US 20010052610 20011220 45 Reduced topography DRAM cell fabricated using a

US 6140684 A 20001031 14 SRAM cell structure with dielectric

US 5892706 A 19990406 43 Fram, fram card, and card system using the

US 5841175 A 19981124 48 Semiconductor device in which an increase in

US 5831300 A 19981103 61 Semiconductor integrated circuit

US 5798964 A 19980825 43 FRAM, FRAM card, and card system using the

US 5683927 A 19971104 9 Method of forming CMOS integrated circuitry

US 5674763 A 19971007 48 Method of manufacturing a semiconductor device

US 5541870 A 19960730 22 Ferroelectric memory and non-volatile memory

US 5426315 A 19950620 17 Thin-film transistor having an inlaid

US 5334861 A 19940802 15 Semiconductor memory cell

Leung, Wingyu et al.

Chan, Tsiu Chiu et al.

Shimizu, Mitsuru et al.

Sugiura, Souichi et al.

Tadaki, Yoshitaka et al.

Shimizu, Mitsuru et al.

Dennison, Charles H. et al.

Sugiura, Souichi et al.

Mihara, Takashi et al.

Pfiester, James R.

Pfiester, James R. et al.

Ready

NUM SORT

3-9-04

L Number	Hits	Search Text	DB	Time stamp
1	21	chan-darin-a.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:13
2	0	chan-darin-a.in. and second adj transistor	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:13
3	14	chan-darin-a.in. and transistor	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:14
4	1	(chan-darin-a.in. and transistor) and source and drain and (silicon adj layer)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:14
5	33	(US-6100124-\$ or US-5937285-\$ or US-5908309-\$ or US-5015595-\$ or US-5273914-\$ or US-4902634-\$ or US-4422885-\$ or US-4771014-\$ or US-4477310-\$ or US-4703551-\$ or US-6501097-\$ or US-4642878-\$ or US-4637124-\$ or US-6235568-\$ or US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.	USPAT; US-PGPUB	2004/03/09 16:15
6	7	((US-6100124-\$ or US-5937285-\$ or US-5908309-\$ or US-5015595-\$ or US-5273914-\$ or US-4902634-\$ or US-4422885-\$ or US-4771014-\$ or US-4477310-\$ or US-4703551-\$ or US-6501097-\$ or US-4642878-\$ or US-4637124-\$ or US-6235568-\$ or US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.) and (second adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:33
7	39	(second adj transistor) and (diffusivity)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:34

8	39	((second adj transistor) and (diffusivity)) not (chan-darin-a.in. ((US-6100124-\$ or US-5937285-\$ or US-5908309-\$ or US-5015595-\$ or US-5273914-\$ or US-4902634-\$ or US-4422885-\$ or US-4771014-\$ or US-4477310-\$ or US-4703551-\$ or US-6501097-\$ or US-4642878-\$ or US-4637124-\$ or US-6235568-\$ or US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:34
9	33	((second adj transistor) and (diffusivity)) not (chan-darin-a.in. ((US-6100124-\$ or US-5937285-\$ or US-5908309-\$ or US-5015595-\$ or US-5273914-\$ or US-4902634-\$ or US-4422885-\$ or US-4771014-\$ or US-4477310-\$ or US-4703551-\$ or US-6501097-\$ or US-4642878-\$ or US-4637124-\$ or US-6235568-\$ or US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.))) and (source and drain)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:34
10	17	((second adj transistor) and (diffusivity)) not (chan-darin-a.in. ((US-6100124-\$ or US-5937285-\$ or US-5908309-\$ or US-5015595-\$ or US-5273914-\$ or US-4902634-\$ or US-4422885-\$ or US-4771014-\$ or US-4477310-\$ or US-4703551-\$ or US-6501097-\$ or US-4642878-\$ or US-4637124-\$ or US-6235568-\$ or US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.))) and (source and drain)) and (silicon adj layer)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:34
-	5	("6100124" or ("6153443" or ("6235568" or ("5940319" or ("5937285")).PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/08/26 11:04
-	9	("5089441" "5168072" "5252501" "5397909" "5403434" "5716861" "5801078" "5908309" "6066523").PN.	USPAT	2003/01/30 19:19
-	2	("5273914" "5290712").PN.	USPAT	2003/01/30 19:21

-	13	("4366613" "4422885" "4477310" "4703551" "4771014" "4786609" "4902634" "4975718" "4987089" "5015595" "5030582" "5132234" "5141890").PN.	USPAT	2003/01/30 19:23
-	1	"6501097"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/30 19:50
-	2	("5403775" "5872031").PN.	USPAT	2003/01/30 19:58
-	6	5937285.URPN.	USPAT	2003/01/30 19:59
-	2	("5403775" "5872031").PN.	USPAT	2003/01/30 20:04
-	6	("4530150" "4562638" "4590663" "4599789" "4637124" "4642878").PN.	USPAT	2003/01/31 15:49
-	6	("4366613" "4488351" "4505024" "4525920" "4530150" "4536944").PN.	USPAT	2003/01/31 15:47
-	58	("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:38
-	35	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 15:56
-	35	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 15:58
-	33	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 15:59
-	33	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:01
-	10	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process) and (oxidi\$3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:07
-	0	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process) and (oxidi\$3)) not (((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:08
-	23	((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process)) not (((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness) and (diffus\$4 or deplet\$4 or dop\$4 or ion\$4) and etch\$4) and (method or process)) and (oxidi\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:08
-	23	("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) not (((("NMOS" and "PMOS" and (second adj transistor) and (deep\$4 with (source))) and thickness)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:39

-	82	(("4103297" "4239346" "4609930" "4618878" "4680580" "4748485" "4818077" "4853760" "4938565" "4949141" "4977105" "4984033" "4996575" "5003356" "5012228" "5017983" "5034788" "5051570" "5055899" "5056895" "5084905" "5091334" "5103277" "5117278" "5124769" "5140391" "5185535" "5196911" "5198379" "5200846" "5227900" "5233211" "5235195" "5246882" "5273921" "5275972" "5281840" "5287205" "5294821" "5308998" "5327001" "5338959" "5359219" "5365079" "5367180" "5371398" "5412240" "5420048" "5424244" "5434433" "5453858" "5461419" "5470793" "5475238" "5485019" "5495119" "5495353" "5497019" "5499123" "5506436" "5567959" "5568288" "5580802" "5604368" "5604380" "5612799" "5641974" "5650637" "5681759" "5696386" "5717224" "5807772" "5818076" "5838508" "5849043" "5899547" "5917221" "5933205" "5963278" "6011277" "6013928" "6054734").PN.	USPAT	2003/01/31 16:43
-	8	((("4103297" "4239346" "4609930" "4618878" "4680580" "4748485" "4818077" "4853760" "4938565" "4949141" "4977105" "4984033" "4996575" "5003356" "5012228" "5017983" "5034788" "5051570" "5055899" "5056895" "5084905" "5091334" "5103277" "5117278" "5124769" "5140391" "5185535" "5196911" "5198379" "5200846" "5227900" "5233211" "5235195" "5246882" "5273921" "5275972" "5281840" "5287205" "5294821" "5308998" "5327001" "5338959" "5359219" "5365079" "5367180" "5371398" "5412240" "5420048" "5424244" "5434433" "5453858" "5461419" "5470793" "5475238" "5485019" "5495119" "5495353" "5497019" "5499123" "5506436" "5567959" "5568288" "5580802" "5604368" "5604380" "5612799" "5641974" "5650637" "5681759" "5696386" "5717224" "5807772" "5818076" "5838508" "5849043" "5899547" "5917221" "5933205" "5963278" "6011277" "6013928" "6054734").PN.) and (transistor and "PMOS" and "NMOS")	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 16:44
-	18084	("NMOS" and "PMOS")	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:38
-	247	((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:39
-	206	((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:40

-	191	((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:40
-	191	(((((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)) and (method or process)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:41
-	191	(((((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)) and (method or process)) and substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:42
-	190	(((((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)) and (method or process)) and substrate and (dop\$4 or depleti\$4 or ion or implant\$4 diffus\$5)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:44
-	172	(((((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)) and (method or process)) and substrate and (dop\$4 or depleti\$4 or ion or implant\$4 diffus\$5)) and (doppant or depletion or implantation or diffusion)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:46
-	18	(((((("NMOS" and "PMOS")) and (partial\$4 near3 remov\$4)) and (source and drain)) and (insulat\$4 or dielectric)) and (method or process)) and substrate and (dop\$4 or depleti\$4 or ion or implant\$4 diffus\$5)) and (doppant or depletion or implantation or diffusion)) and ((second adj region) or (second adj portion))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/31 17:47
-	4	("5097314" "5461253" "5627399" "5754077").PN.	USPAT	2003/01/31 17:52
-	1	6060748.URPN.	USPAT	2003/01/31 17:54
-	2777	("NMOS" and "PMOS" and (transistor with (partial\$4 (etch\$4 or remov\$4))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:50
-	3211	("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:52
-	581	("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:52
-	3284	((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or ((("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))) and (method or process)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:54
-	3008	((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or ((("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))) and (method or process)) and (insulat\$4 or dielectric\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:55
-	951	(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or ((("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:55

-	92	(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:56
-	80	(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor)) and (source and drain and gate)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 14:58
-	15	(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor)) and (source and drain and gate)) and (second adj portion)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 15:13
-	65	(((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor)) and (source and drain and gate)). not (((((("NMOS" and "PMOS" and (substrate with (partial\$4 (etch\$4 or remov\$4)))) or (("NMOS" and "PMOS" and ((silicon adj layer) with (partial\$4 (etch\$4 or remov\$4)))))) and (method or process)) and (insulat\$4 or dielectric\$4)) and (oxidi\$3)) and (second adj transistor)) and (source and drain and gate)) and (second adj portion))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/02/03 15:13
-	1	"20020179957"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/04/30 10:02
-	0	20020179957.URPN.	USPAT	2003/04/29 17:55
-	8	"5111255"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/04/30 10:02
-	8	("4558337" "4590502" "4686550" "4800415" "4806997" "4814836" "4860068" "4862228").PN.	USPAT	2003/04/30 10:03
-	7	5111255.URPN.	USPAT	2003/04/30 10:04
-	3	("4825264" "5111255" "5162877").PN.	USPAT	2003/04/30 14:48
-	8	("4558337" "4590502" "4686550" "4800415" "4806997" "4814836" "4860068" "4862228").PN.	USPAT	2003/04/30 14:49
-	7	5111255.URPN.	USPAT	2003/04/30 14:50
-	523	((semiconductor adj layer) with etch\$4) and (isolation adj region)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:24
-	484	((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:44

-	66	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:45
-	59	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:45
-	40	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor and oxidiz\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:45
-	39	((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4 and (mask)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:46
-	0	((((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) and resist) and antireflect\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:47
-	0	((((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) and resist) and (anti adj reflect\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 01:47
-	29	((((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) and resist	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:02
-	14	("4314267" "4609931" "4612629" "4672416" "4830973" "4939563" "4947192" "5034782" "5040041" "5075250" "5140400" "5177584" "5412240" "5434441").PN.	USPAT	2003/05/05 01:57
-	10	((((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) not (((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) and resist)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:04
-	127	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:10
-	112	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:06
-	112	((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:06
-	0	((((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)) and (mask and resist and oxidez\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:07

-	26	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)) and (mask and resist)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:07
-	21	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)) and (mask and resist)) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:07
-	12	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and (lower adj (portion or region or section or area)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:10
-	11	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and (lower adj (portion or region or section or area))) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)) and (mask and resist)) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:11
-	11	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and (lower adj (portion or region or section or area))) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (lower adj (portion or region or section or area))) and (insulat\$4 adj layer)) and (substrate and etch\$4)) and (mask and resist)) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask))) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask)) and resist) and antireflect\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:13
-	523	((semiconductor adj layer) with etch\$4) and (isolation adj region)) and ((semiconductor adj layer) same etch\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:14
-	523	((semiconductor adj layer) with etch\$4) and (isolation adj region)) and ((semiconductor adj layer) with etch\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:14

-	27	(((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) not ((((((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate)) and transistor) and oxidiz\$4) and (mask))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:21
-	4	((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (lower adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:21
-	7	("5623155" "5729039" "5973364" "6191449" "6288425" "6348714" "6414355" "2002/0048972").PN.	USPAT	2003/05/05 02:22
-	592	substrate and insulat\$4 and (isolati\$3 adj region) and (second adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:57
-	86	(substrate and insulat\$4 and (isolati\$3 adj region) and (second adj transistor)) and (mask and resist and oxidiz\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:26
-	85	((substrate and insulat\$4 and (isolati\$3 adj region) and (second adj transistor)) and (mask and resist and oxidiz\$4)) and etch\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:28
-	80	((substrate and insulat\$4 and (isolati\$3 adj region) and (second adj transistor)) and (mask and resist and oxidiz\$4)) and etch\$4) not (((semiconductor adj layer) with etch\$4) and (isolation adj region)) and (insulat\$4)) and (insulati\$4 adj substrate))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 02:28
-	0	20020125512.URPN.	USPAT	2003/05/05 02:34
-	10	(substrate and insulat\$4 and (isolati\$3 adj region) and (second adj transistor)) and (lower adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 03:00
-	713	("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 03:01
-	3	"6037632"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:32
-	7	("4422089" "5132769" "5177572" "5438215" "5488236" "5510634" "5572048").PN.	USPAT	2003/05/05 10:34
-	2	6037632.URPN.	USPAT	2003/05/05 10:36
-	0	("535" and (second adj transistor)) and (fully adj depleted adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:41
-	0	("535" and (second adj transistor)) and (partially adj depleted adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:42
-	123	("535" and (second adj transistor)) and ("NMOS" and "PMOS")	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:42
-	11	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:43

-	11	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 10:47
-	486	"535" and (second adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:04
-	535	((("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)) and transistor and etch\$4) and insulat\$3	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:08
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and (isolati\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:15
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and (isolat\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:16
-	112	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:51
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and (isolat\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:17
-	112	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and transistor	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:17
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and transistor) and (isolat\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:18
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and transistor) and (isolati\$3 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:18
-	0	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resist or photoresist))) and transistor) and (trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:18
-	483	((("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)) and transistor and etch\$4) and insulat\$3 and (isolati\$4 adj trench)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:18
-	65	((("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)) and transistor and etch\$4) and insulat\$3 and (isolati\$4 adj trench)) and (("PMOS" and "NMOS") and (isolat\$4 adj trench))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:50
-	9	("4090254" "4276616" "4677589" "4933899" "5027323" "5038191" "5060194" "5757693" "5761114").PN.	USPAT	2003/05/05 11:36
-	19	5909400.URPN.	USPAT	2003/05/05 11:39
-	2	("5898196" "5909400").PN.	USPAT	2003/05/05 11:42

-	0	6180986.URPN.	USPAT	2003/05/05 11:43
-	19	5909400.URPN.	USPAT	2003/05/05 11:44
-	112	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resisk or photoresist))) and transistor) not ((((((("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)) and transistor and etch\$4) and insulat\$3) and (isolati\$4 adj trench)) and ((("PMOS" and "NMOS") and (isolat\$4 adj trench))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 11:51
-	112	((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) not (((("535" and (second adj transistor)) and ("NMOS" and "PMOS")) and (mask or resisk or photoresist))) not ((((((("silicon-on-insulator" or "SOI") and (isolat\$4 adj trench)) and transistor and etch\$4) and insulat\$3) and (isolati\$4 adj trench)) and ((("PMOS" and "NMOS") and (isolat\$4 adj trench))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 12:01
-	20	"5909400"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 15:17
-	2	("5898196" "5909400").PN.	USPAT	2003/05/05 12:03
-	2	((("5,909,400") or ("20010045561"))).PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/05/05 15:17
-	11	"5940691"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/08/21 15:00
-	19	"5463238"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/08/21 15:01
-	30	"5940691" or "5463238"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/08/21 15:01
-	7	("3783052" "4725875" "4753896" "4816893" "4819052" "5081062" "5164803").PN.	USPAT	2003/08/21 15:12
-	3	((("5940691") or ("6110765") or ("5463238"))).PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/08/26 11:05
-	41	en-william-g.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:38
-	10	pellerin-john-g.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:38
-	110	michael-mark-w.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:39
-	0	mark-michael-w.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:39

-	157	en-william-g.in. pellerin-john-g.in. michael-mark-w.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:39
-	100	((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:39
-	98	((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain) and (second transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:40
-	5	((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain) and (second adj transistor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:42
-	10	((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain) and (second adj source)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:42
-	9	((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain) and (second adj source)) not (((en-william-g.in. pellerin-john-g.in. michael-mark-w.in.) and source and drain) and (second adj transistor))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/09 16:13
-	410	(second adj transistor) and (buried adj layer)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:44
-	410	((second adj transistor) and (buried adj layer)) not (en-william-g.in. pellerin-john-g.in. michael-mark-w.in.)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:44
-	31	((second adj transistor) and (buried adj layer)) not (en-william-g.in. pellerin-john-g.in. michael-mark-w.in.)) and (second adj source)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/11/21 14:44
-	33	(US-6440832-\$ or US-5963278-\$ or US-5899547-\$ or US-5937285-\$ or US-6100124-\$ or US-5908309-\$ or US-5273914-\$ or US-5015595-\$ or US-4477310-\$ or US-4902634-\$ or US-4703551-\$ or US-4771014-\$ or US-4422885-\$ or US-6501097-\$ or US-4637124-\$ or US-4642878-\$ or US-6235568-\$ or US-6060748-\$ or US-5627399-\$ or US-6420730-\$ or US-5834350-\$ or US-5428224-\$ or US-5162877-\$ or US-5909400-\$ or US-6180986-\$ or US-6537891-\$).did. or (US-5463238-\$ or US-5164803-\$).did. or (US-20020195623-\$ or US-20010016377-\$ or US-20020130393-\$ or US-20020102780-\$ or US-20020171077-\$).did.	USPAT; US-PGPUB	2003/11/21 15:03
-	20	("3894891" "4153904" "4313971" "5488579" "5594371" "5670387" "5670388" "5767549" "5789286" "5811855" "5821769" "5877046" "5929476" "5940691" "5985683" "5985728" "6054345" "6061268" "6084259" "6144072").PN.	USPAT	2003/11/21 15:19
-	0	6537891.URPN.	USPAT	2003/11/21 15:21
-	0	6537891.URPN.	USPAT	2003/11/21 15:21